



DECLARATION

As a below-named inventor, I hereby declare that:

My correct residence, post office address and citizenship are stated below next to my name.

I believe myself to be the original, first and sole inventor (if only one name is listed below) or an original and first joint inventor (if more than one name is listed below) of the subject matter which is disclosed and claimed and for which a patent is sought on the invention entitled:

"Dedicated Interface Architecture for a Hybrid Integrated Circuit"

The specification of this subject matter:

- ☐ is attached hereto.
- ☒ was filed on April 28, 1998;
- was assigned serial No. 09/069,054;
- which was amended on _____.

I hereby state that I have reviewed and understand the contents of the above identified patent application, including the claims, as amended by any amendment(s) referred to above. I believe the subject matter claimed in the above-identified application to be new and to be unobvious to persons of ordinary skill in the art in view of the prior art of which I am aware. I further hereby state that the specification of the above identified patent application adequately describes how to make and use the claimed invention, and further that it sets forth the best mode for practicing the invention known to me as of the date that the application was filed. I acknowledge the duty to disclose information which is material to the examination of this application in accordance with 37 C.F.R. §1.56(a).

I hereby claim foreign priority benefits under 35 U.S.C. §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed.

Application No.	Country	Filing Date	Priority Claimed
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I hereby claim the benefit under 35 U.S.C. §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in these prior United States application(s) in the manner provided by 35 U.S.C. §112, I acknowledge the duty to disclose material information as defined in 37 C.F.R. §1.56(a) which occurred between the filing date of the prior application(s) and the national or PCT international filing date of this application.

Application No.	Filing Date	Status (Issued, Pending, Abandoned)
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GROUP 1200
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FULL NAME OF INVENTOR 1	FIRST Name	MIDDLE Initial(s)	LAST Name	
	King	W.	Chan	
RESIDENCE AND CITY	City	State or Foreign Country	Country of Citizenship	
	Los Altos	California	United States of America	
POST OFFICE ADDRESS	Number and Street	City	State or Country	Zip Code
	697 Riverside Drive	Los Altos	California	94024

FULL NAME OF INVENTOR 2	FIRST Name	MIDDLE Initial(s)	LAST Name	
	William	C. T.	Shu	
RESIDENCE AND CITY	City	State or Foreign Country	Country of Citizenship	
	Palo Alto	California	United States of America	
POST OFFICE ADDRESS	Number and Street	City	State or Country	Zip Code
	2155 Harvard Street	Palo Alto	California	94306


FULL NAME OF INVENTOR 3	FIRST Name	MIDDLE Initial(s)	LAST Name	
	Sinan		Kaptanoglu	
RESIDENCE AND CITY	City	State or Foreign Country	Country of Citizenship	
	BELMONT San Carlos	California	United States of America	
POST OFFICE ADDRESS	Number and Street	City	State or Country	Zip Code
	2701 WITHERIDGE RD. 2813 San Simeon Way	BELMONT San Carlos	California	94002 94070

FULL NAME OF INVENTOR 4	FIRST Name	MIDDLE Initial(s)	LAST Name	
	Chi	Fung	Cheng	
RESIDENCE AND CITY	City	State or Foreign Country	Country of Citizenship	
	San Jose	California	Hong Kong	
POST OFFICE ADDRESS	Number and Street	City	State or Country	Zip Code
	3079 Florence Park Drive	San Jose	California	95135

I further declare that all statements made herein of my own knowledge are true and that all statements made upon information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

<u>Xing W. Chan</u>	<u>7/20/98</u>	<u>William Shu</u>	<u>7/20/98</u>
Signature of Inventor 1	Date	Signature of Inventor 2	Date

Signature of Inventor 3	Date	Signature of Inventor 4	Date
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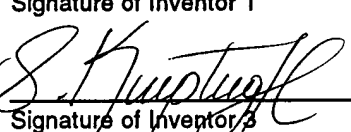
FULL NAME OF INVENTOR 1	FIRST Name	MIDDLE Initial(s)	LAST Name	
	King	W.	Chan	
RESIDENCE AND CITY	City	State or Foreign Country	Country of Citizenship	
	Los Altos	California	United States of America	
POST OFFICE ADDRESS	Number and Street	City	State or Country	Zip Code
	697 Riverside Drive	Los Altos	California	94024

FULL NAME OF INVENTOR 2	FIRST Name	MIDDLE Initial(s)	LAST Name	
	William	C. T.	Shu	
RESIDENCE AND CITY	City	State or Foreign Country	Country of Citizenship	
	Palo Alto	California	United States of America	
POST OFFICE ADDRESS	Number and Street	City	State or Country	Zip Code
	2155 Harvard Street	Palo Alto	California	94306

FULL NAME OF INVENTOR 3	FIRST Name	MIDDLE Initial(s)	LAST Name	
	Sinan		Kaptanoglu	
RESIDENCE AND CITY	City	State or Foreign Country	Country of Citizenship	
	Belmont	California	United States of America	
POST OFFICE ADDRESS	Number and Street	City	State or Country	Zip Code
	2701 Witheridge Road	Belmont	California	94002

FULL NAME OF INVENTOR 4	FIRST Name	MIDDLE Initial(s)	LAST Name	
	Chi	Fung	Cheng	
RESIDENCE AND CITY	City	State or Foreign Country	Country of Citizenship	
	San Jose	California	Hong Kong	
POST OFFICE ADDRESS	Number and Street	City	State or Country	Zip Code
	3079 Florence Park Drive	San Jose	California	95135

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Signature of Inventor 1	Date	Signature of Inventor 2	Date
	8/14/98		
Signature of Inventor 3	Date	Signature of Inventor 4	Date